



Electronic Textile Materials: Materials, Fabrication and Application

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Message from the Guest Editors

Dear Colleagues,

The usual interface of human skin is textile, with more than 80% of our body continuously covered of textile. For this reason, electronic textile (e-textile) materials have been introduced as emerging concepts in order to enable humans' garments to interact with technological anthropic surroundings. Those intelligent application textiles have been called e-garments or smart textiles, and they can potentially be used in many application areas, such as healthcare, sports, emergency and law enforcement work, electromagnetic hazardous environment work, military, space, casual daily clothes, and fashion.

This Special Issue aims to publish new and novel research work focusing on the latest advances in e-textile technologies. Major subtopics include materials and the fabrication and application of e-textiles. These can be considered in relation to design computational simulation, experimental characterization, modelling, reliability, and applications.

It is our pleasure to invite you to submit a manuscript to this Special Issue. Full papers, communications, and reviews are all welcome.





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Message from the Editor-in-Chief

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